

Features

- Advanced trench process technology
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high EAS
- Fast Switching
- High Ruggedness

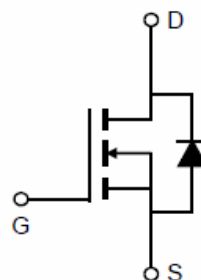
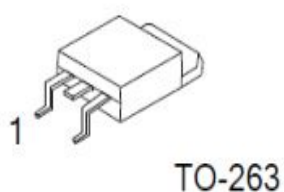
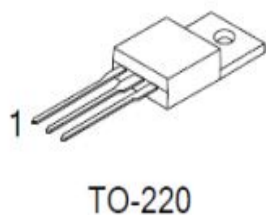
Product Summary

V _{DS}	80V
R _{DS(on)} @V _{GS} =10V	5.5 mΩ
I _D	120A

Application

- Power switching application
- UPS (Uninterruptible Power Supplies)
- DC/DC converter
- General purpose applications

Part ID	Package Type	Marking
SFP120N80B	TO-220	120N80B
SFB120N80B	TO-263	120N80B



Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V _{DS}	80	V
Continuous drain current T _C = 25°C (Silicon limit)	I _D	120	A
T _C = 100°C (Silicon limit)		90	
Pulsed drain current T _C = 25°C, t _p limited by T _{jmax}		450	
Avalanche energy, single pulse (L=1mH, R _g =25Ω, I _D =sweep(14A~46A))	E _{AS}	1200	mJ
Gate-emitter voltage	V _{GS}	±20	V
Power dissipation T _C = 25°C	P _{tot}	220	W
Operating junction and storage temperature	T _j , T _{stg}	-55...+150	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R_{thJC}	0.66	°C/W
Thermal resistance, junction – ambient. Max	R_{thJA}	62.0	

Electrical Characteristic, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Test Condition	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	88	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$ $T_j=25^{\circ}C$ $T_j=125^{\circ}C$	2.0 -	2.8	4.0 -	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=80V, V_{GS}=0V$ $T_j=25^{\circ}C$ $T_j=125^{\circ}C$	- -	0.05 -	1 5	
Gate-source leakage current	I_{GSS}	$V_{GS}=20V, V_{DS}=0V$	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=40A,$ $T_j=25^{\circ}C$ $T_j=125^{\circ}C$	- -	5.5 -	6.5 -	m Ω

Dynamic Characteristic

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=25V,$ $f=1MHz$	-	5300	-	pF
Output Capacitance	C_{oss}		-	860	-	
Reverse Transfer Capacitance	C_{rss}		-	420	-	
Gate Total Charge	Q_G	$V_{GS}=10V, V_{DS}=30V,$ $I_D=30A, f=1MHz$	-	125	-	nC
Gate-Source charge	Q_{gs}		-	20.0	-	
Gate-Drain charge	Q_{gd}		-	45.0	-	
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ C, V_{GS}=10V,$ $V_{DS}=30V, R_L=15\Omega$	-	35.2	-	ns
Rise time	t_r		-	38.9	-	
Turn-off delay time	$t_{d(off)}$		-	45.1	-	
Fall time	t_f		-	22.8	-	

Body Diode Characteristic

Body Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=40A$	-	0.75	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F=40A,$ $dI/dt=100A/\mu s$		60		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=40A,$ $dI/dt=100A/\mu s$		76		nC

Typical Performance Characteristics

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

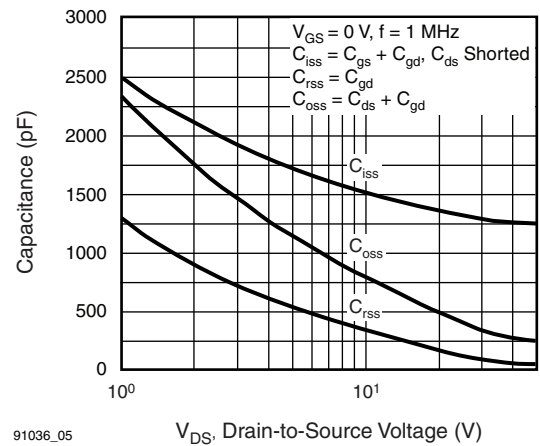
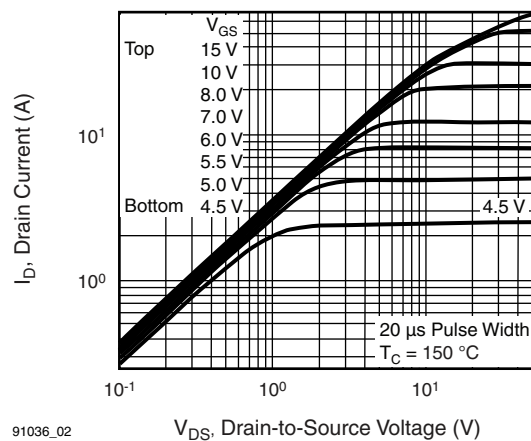
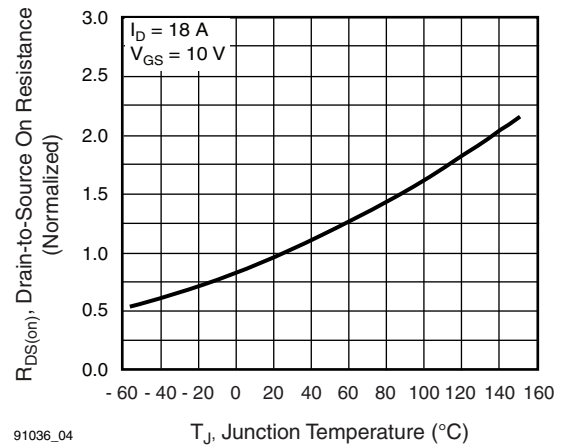
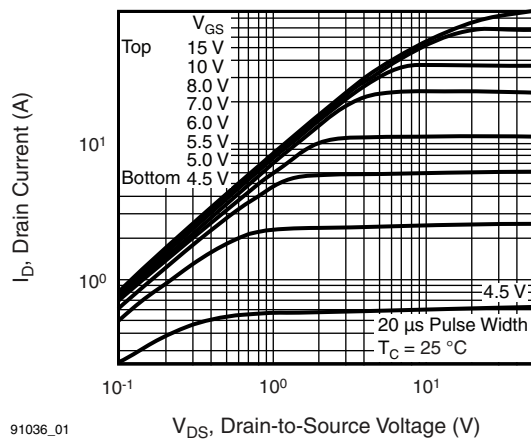
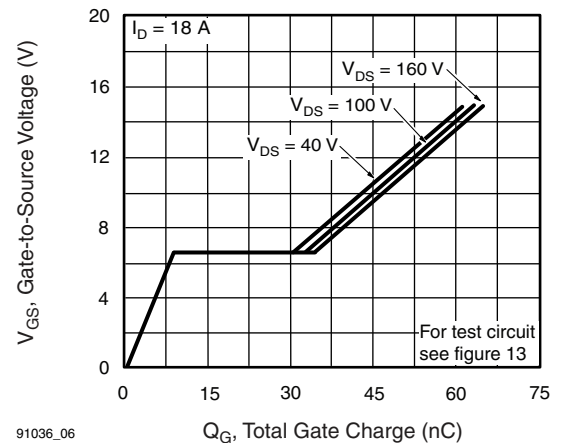
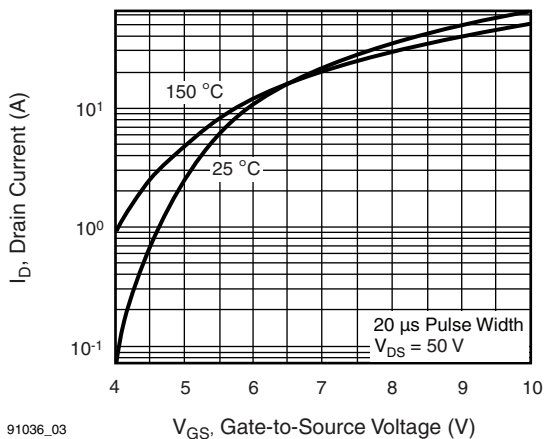


Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ }^{\circ}\text{C}$

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



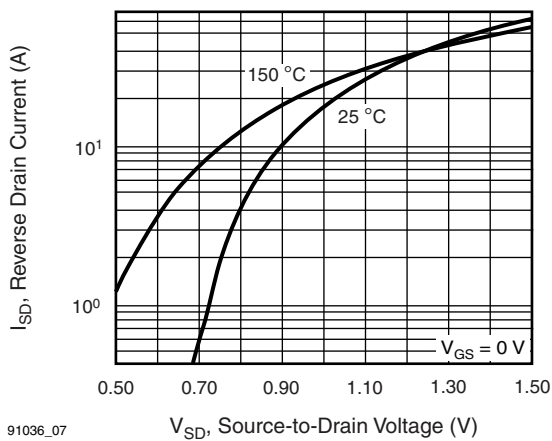


Fig. 7 - Typical Source-Drain Diode Forward Voltage

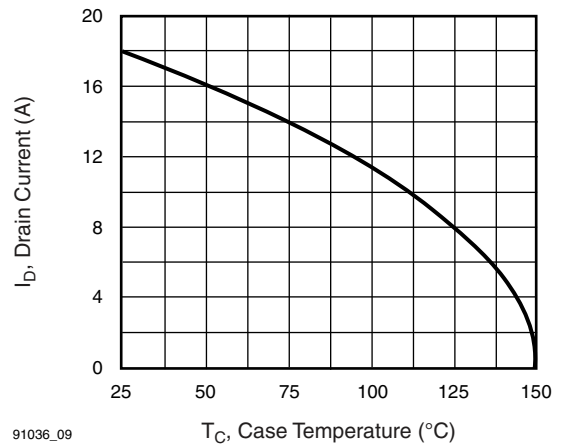


Fig. 9 - Maximum Drain Current vs. Case Temperature

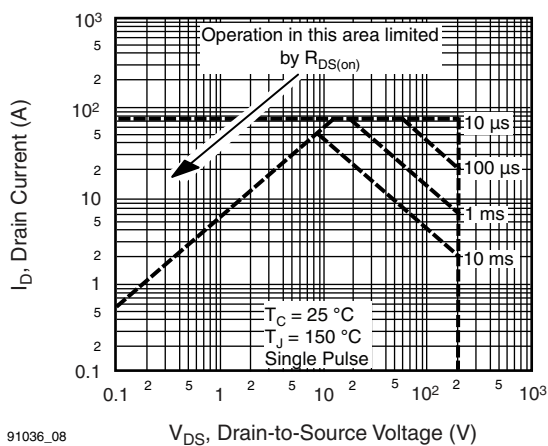


Fig. 8 - Maximum Safe Operating Area

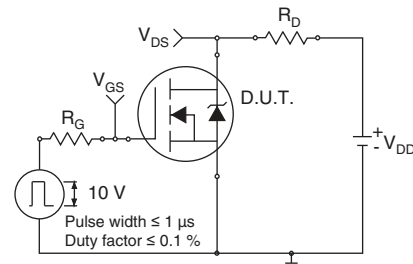


Fig. 10a - Switching Time Test Circuit

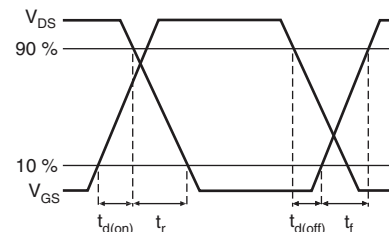


Fig. 10b - Switching Time Waveforms

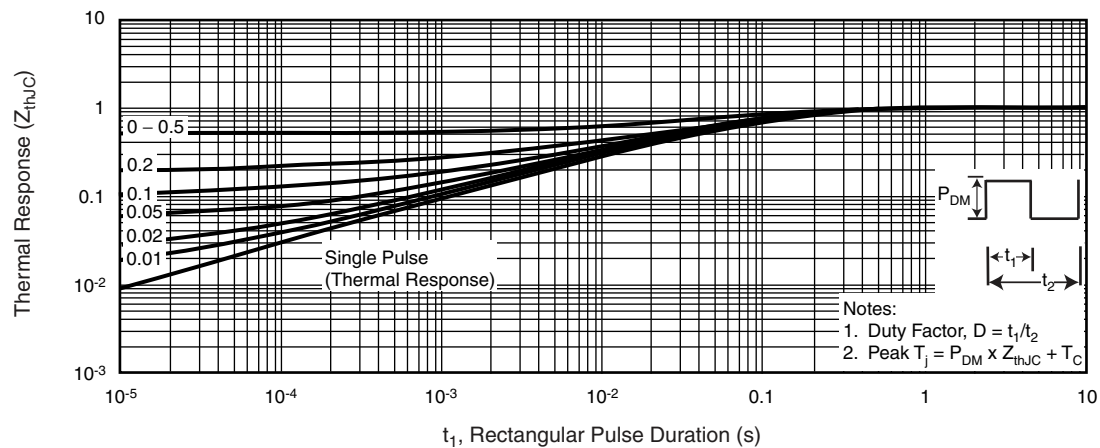


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

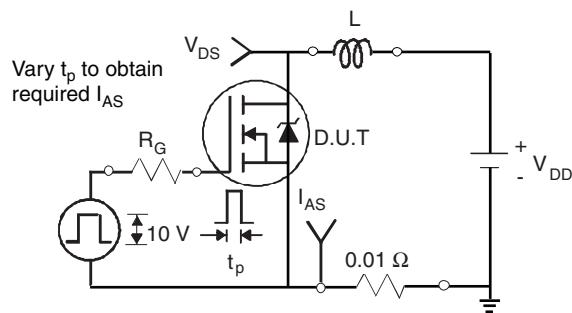


Fig. 12a - Unclamped Inductive Test Circuit

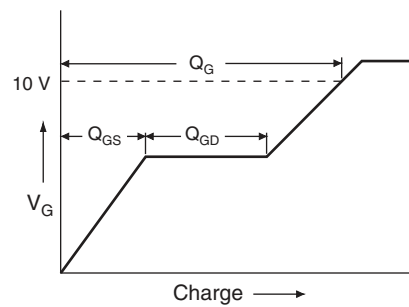


Fig. 13a - Basic Gate Charge Waveform

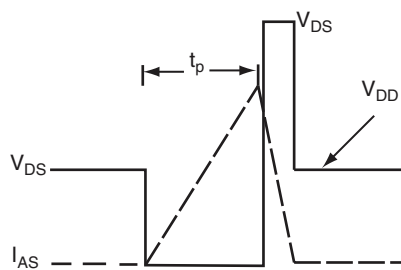


Fig. 12b - Unclamped Inductive Waveforms

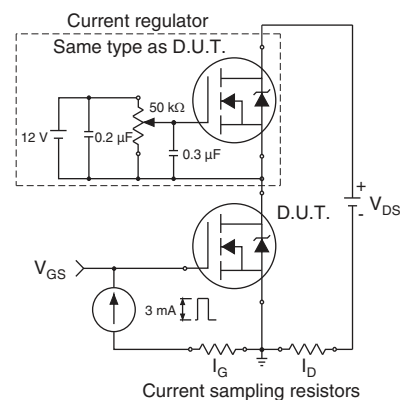
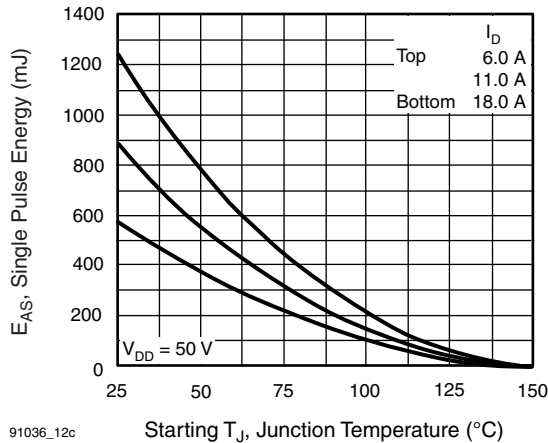


Fig. 13b - Gate Charge Test Circuit

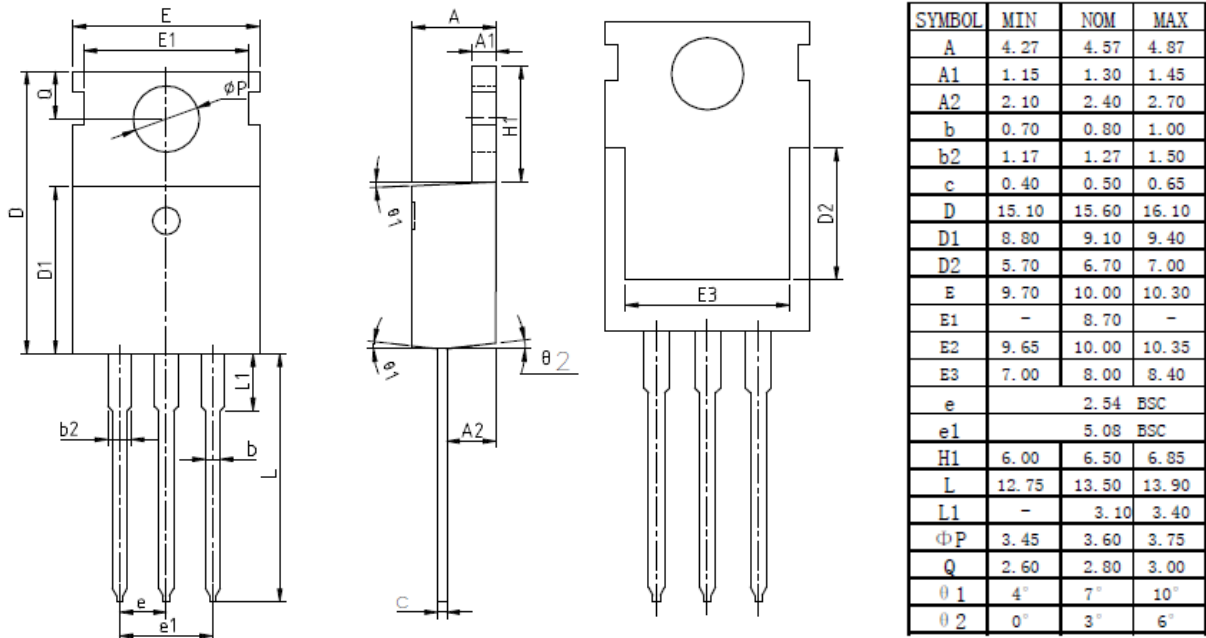


91036_12c

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

PACKAGE DIMENSION

TO-220



TO-263

